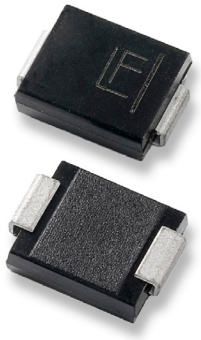
3.0SMC Series
Surface Mount

HF RoHS Pb e3

Uni-directional



Additional Information

Resources | Accessories | Samples

Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Power Dissipation on Infinite Heat Sink at T_L=50°C	P_D	6.5	W
Peak Forward Surge Current, 8.3ms Single Half Sine Wave (Note 1)	I_{FSM}	300	A
Maximum Instantaneous Forward Voltage at 100A for Unidirectional Only	V_F	3.5	V
Operating Temperature Range	T_J	-65 to 150	°C
Storage Temperature Range	T_{STG}	-65 to 175	°C
Typical Thermal Resistance Junction to Lead	$R_{\theta JL}$	15	°C/W
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	75	°C/W

Notes:
1. Measured on 8.3ms single half sine wave or equivalent square wave for unidirectional device only, duty cycle = 4 per minute maximum.

Description

The 3.0SMC series is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

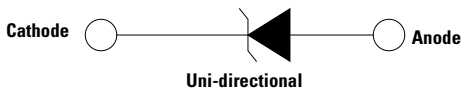
Features & Benefits

- For surface mounted applications in order to optimize board space
- Low profile package
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC-61000-4-2 ESD 30kV(Air), 30kV (Contact)
- I_{PP} is specified @ 8/20μS surge waveform
- Built-in strain relief
- V_{BR}@T_J= V_{BR}@25°C x (1+αT x (T_J - 25))(αT:Temperature Coefficient, typical value is 0.1%)
- Glass passivated chip junction
- Fast response time: typically less than 1.0ps from 0V to BV min
- Excellent clamping capability
- Low incremental surge resistance
- High temperature to reflow soldering guaranteed: 260°C/40sec
- Meet MSL level1, per J-STD-020, LF maximun peak of 260°C
- Matte tin lead–free plated
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

Applications

TVS devices are ideal for the protection of I/O Interfaces, V_{CC} bus and other vulnerable circuits used in Telecom, Computer, Industrial and Consumer electronic applications.

Functional Diagram



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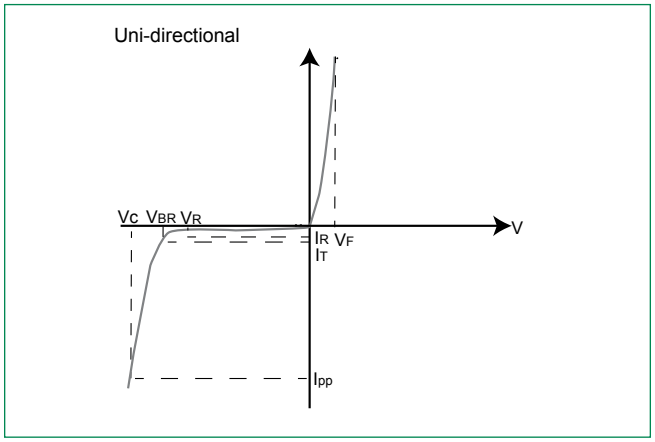
Surface Mount

Electrical Characteristics (T_A=25°C unless otherwise noted)

Part Number (Uni)	Marking	Reverse Stand off Voltage V_R (Volts)	Breakdown Voltage V_{BR} (Volts) @ I_T		Test Current I_T (mA)	Maximum Clamping Voltage V_C @ 8/20µS I_{pp} (V)	Maximum Peak Pulse Current I_{pp} @ 8/20µS (A)	Maximum Reverse Leakage I_R @ V_R (µA)
			MIN	MAX				
3.0SMC20A	YLA	20.0	22.20	24.50	1	42	570	1
3.0SMC24A	YLC	24.0	26.70	29.50	1	51	520	1
3.0SMC28A	YLE	28.0	31.10	34.40	1	59	470	1
3.0SMC30A	YLF	30.0	33.30	36.80	1	62	420	1
3.0SMC33A	YLG	33.0	36.70	40.60	1	70	365	1

I-V Curve Characteristics



P_{PPM} Peak Pulse Power Dissipation – Max power dissipation
V_R Stand-off Voltage – Maximum voltage that can be applied to the TVS without operation
V_{BR} Breakdown Voltage – Maximum voltage that flows though the TVS at a specified test current (I_T)
V_C Clamping Voltage – Peak voltage measured across the TVS at a specified Ippm (peak impulse current)
I_R Reverse Leakage Current – Current measured at V_R
V_F Forward Voltage Drop for Uni-directional

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

Figure 1 - TVS Transients Clamping Waveform

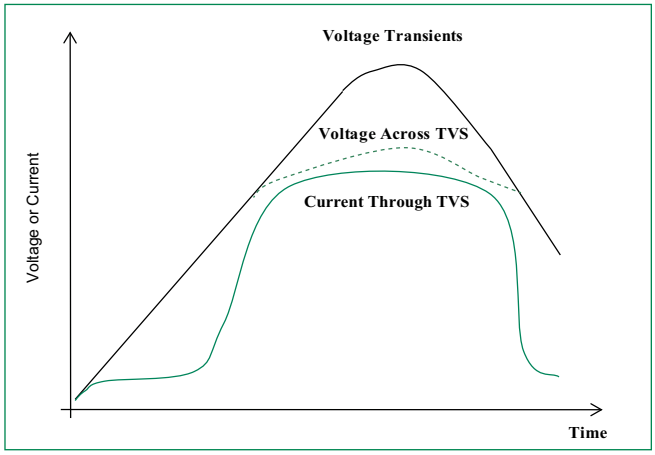
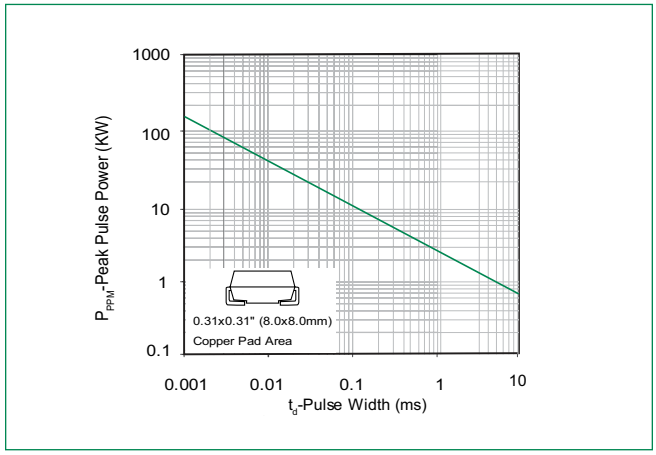


Figure 2 - Peak Pulse Power Rating



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Surface Mount

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted) (Continued)

Figure 3 - Peak Pulse Power Derating Curve

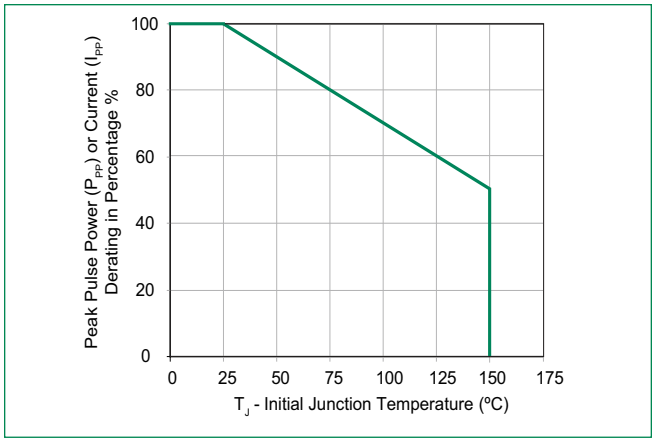


Figure 4 - Pulse Waveform

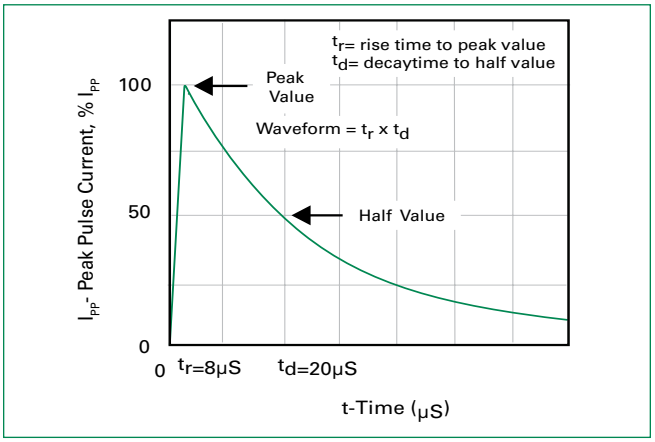


Figure 5 - Typical Junction Capacitance

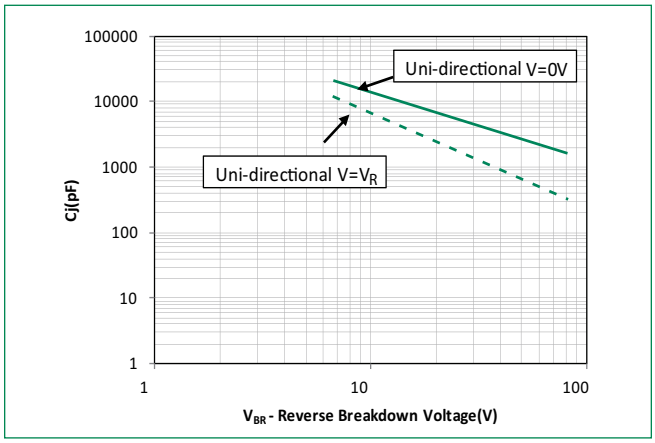


Figure 6 - Typical Transient Thermal Impedance

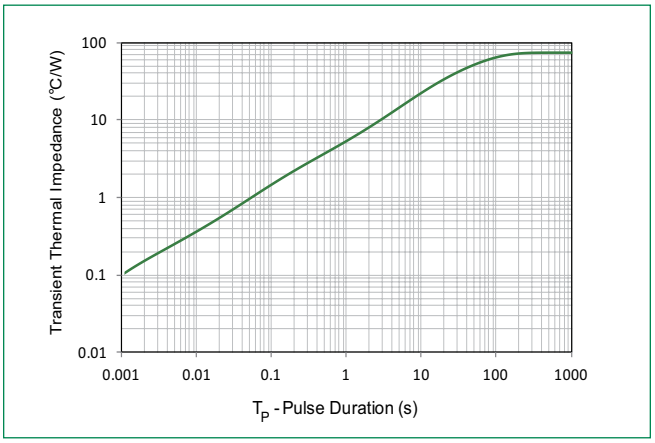


Figure 7 - Maximum Non-Repetitive Peak Forward Surge Current Uni-Directional only

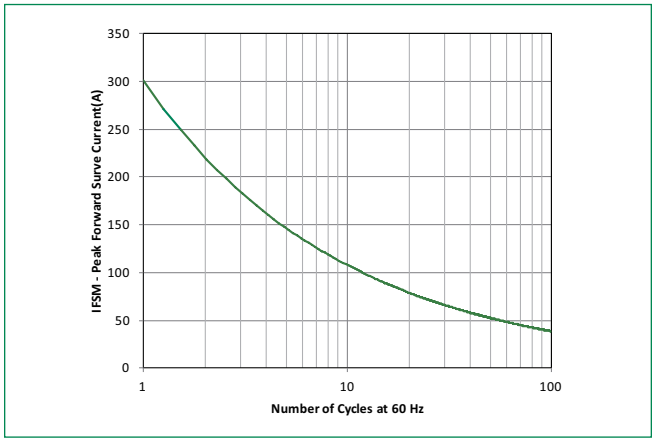
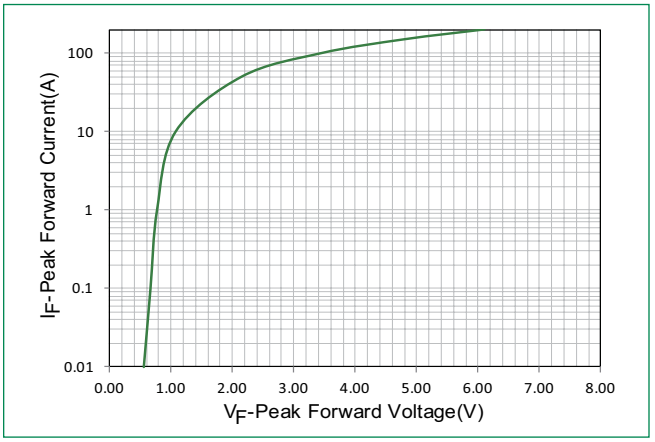


Figure 8 - Peak Forward Voltage Drop vs Peak Forward Current (Typical Values)



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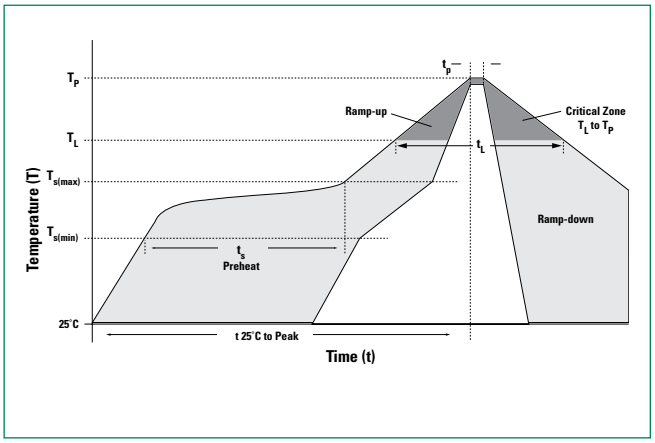
Surface Mount

Soldering Parameters

Reflow Condition		Lead–free assembly
Pre Heat	**- Temperature Min ($T_{s(min)}$)**	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_A) to peak		3°C/second max
$T_{S(max)}$ to T_A - Ramp-up Rate		3°C/second max
Reflow	**- Temperature (T_A) (Liquidus)**	217°C
	- Time (min to max) (t_s)	60 – 150 seconds
Peak Temperature (T_P)		$260^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		260°C



Physical Specifications

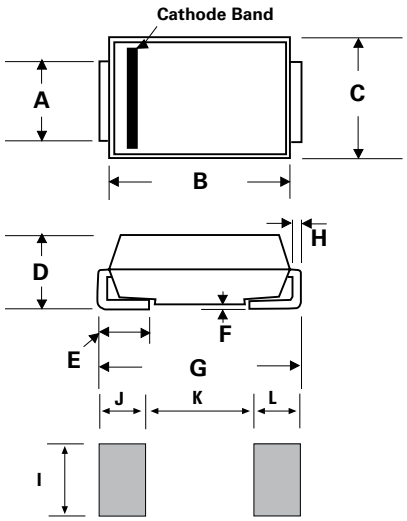
Weight	0.007 ounce, 0.21 grams
Case	JEDEC DO214AB. Molded plastic body over glass passivated junction
Polarity	Color band denotes positive end (cathode) except Bidirectional.
Terminal	Matte Tin-plated leads, Solderable per JESD22-B102

Environmental Specifications

High Temp. Storage	JESD22-A103
HTRB	JESD22-A108
Temperature Cycling	JESD22-A104
MSL	JEDEC-J-STD-020, Level 1
H3TRB	JESD22-A101
RSH	JESD22-A111

Dimensions

DO-214AB (SMC J-Bend)



Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.114	0.126	2.900	3.200
B	0.260	0.280	6.600	7.110
C	0.220	0.245	5.590	6.220
D	0.079	0.103	2.060	2.620
E	0.030	0.060	0.760	1.520
F	-	0.008	-	0.203
G	0.305	0.320	7.750	8.130
H	0.006	0.012	0.152	0.305
I	0.129	-	3.300	-
J	0.094	-	2.400	-
K	-	0.165		4.200
L	0.094	-	2.400	-

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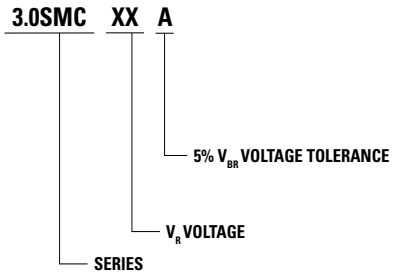
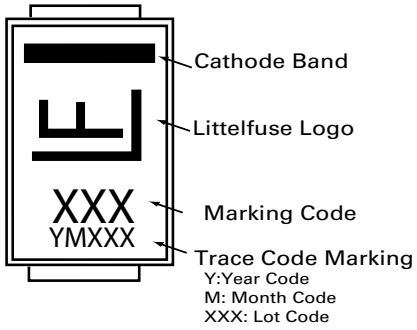
Part Numbering System



Part Marking System



Packaging Options

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
3.0SMCxxX	DO-214AB	3000	Tape & Reel - 16mm tape/13"reel	EIA STD RS-481

Tape and Reel Specification